IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (previously amended) A lead-free solder paste including a plurality of different types of metal powder mixed with a flux, one of the metal powders being a Sn alloy powder, another of the metal powders being selected from a Sn alloy powder, elemental Ag powder, elemental Cu powder, and elemental Sn powder, each Sn alloy powder including 0 - 8 mass % of Ag, 0 - 5 mass % of Cu, and at least 80 mass % of Sn, the plurality of metal powders having a composition when melted of 1 - 5 mass % Ag, at least 0.5 and less than 3 mass % Cu, and a remainder of Sn.

2. (original) A solder paste as claimed in claim 1 wherein one of the metal powders comprises an elemental metal powder of Ag, Cu or Sn.

3. (previously amended) A lead-free solder paste including a plurality of different types of metal powder mixed with a flux, the plurality of metal powders including two different Sn alloy powders, each Sn alloy powder including 0 - 8 mass % of Ag, 0 - 5 mass % of Cu, and at least 80 mass % of Sn, the plurality of metal powders having a composition when melted of 1 - 5 mass % Ag, 0.5 - 3 mass % Cu, and a remainder of Sn.

4. (original) A solder paste as claimed in claim 3 wherein the two Sn alloy powders contain the same components as each other in different proportions.

5. (previously amended) A solder paste as claimed in claim 3 wherein the plurality of metal powders include two different Sn-Ag-Cu alloy powders.

6. (previously amended) A solder paste as claimed in claim 3 wherein one of the metal powders is a Sn-Ag alloy powder and another of the metal powders is a Sn-Cu alloy powder.

7. (previously amended) A solder paste as claimed in claim 3 wherein the plurality of metal powders include a Sn-Ag alloy powder, a Sn-Cu alloy powder, and a Sn-Ag-Cu alloy powder.

8. (currently amended) A method ~~of soldering a surface mounted device comprising performing reflow soldering using the solder paste of claim 3~~ as claimed in claim 17, wherein the plurality of metal powders include two different Sn alloy powders.

9. (original) A method as claimed in claim 8 including performing the reflow soldering at a reflow temperature of at most 250°C.

10. (original) A method as claimed in claim 9 wherein the

reflow temperature is at most 240°C.

11. (original) A method as claimed in claim 8 wherein the surface mounted device comprises a chip component.

12. (original) A method as claimed in claim 8 including printing the solder paste on a printed circuit board.

13. (previously presented) A solder paste as claimed in claim 1 wherein the plurality of metal powders have a composition when melted containing at most 1.0 mass % of Cu.

14. (previously presented) A solder paste as claimed in claim 3 wherein the plurality of metal powders have a composition when melted containing less than 3.0 mass % of Cu.

15. (previously presented) A solder paste as claimed in claim 3 wherein the plurality of metal powders have a composition when melted containing at most 1.0 mass % of Cu.

16. (previously presented) A method as claimed in claim 8 including melting the plurality of metal powders in the solder paste during the reflow soldering.

17. (currently amended) A method of soldering a surface mounted device comprising performing reflow soldering using ~~the solder paste of claim 1~~ a lead-free solder paste including a

plurality of different types of metal powder mixed with a flux, one of the metal powders being a Sn alloy powder, another of the metal powders being selected from a Sn alloy powder, elemental Ag powder, elemental Cu powder, and elemental Sn powder, each Sn alloy powder including 0 - 8 mass % of Ag, 0 - 5 mass % of Cu, and at least 80 mass % of Sn, the plurality of metal powders having a composition when melted of 1 - 5 mass % Ag, at least 0.5 and less than 3 mass % Cu, and a remainder of Sn, the reflow soldering including melting the plurality of metal powders in the solder paste.

Claim 18 (cancelled)

19. (previously presented) A method as claimed in claim 16 including completely melting the plurality of metal powders in the reflow soldering.

20. (previously presented) A method as claimed in claim 19 including completely melting the plurality of metal powders in a single reflow step.

21. (previously presented) A method as claimed in claim 17 including completely melting the plurality of metal powders in the reflow soldering.

22. (previously presented) A method as claimed in claim 21 including completely melting the plurality of metal powders in a

single reflow step.

Claim 23 (cancelled)

Claim 24 (cancelled)